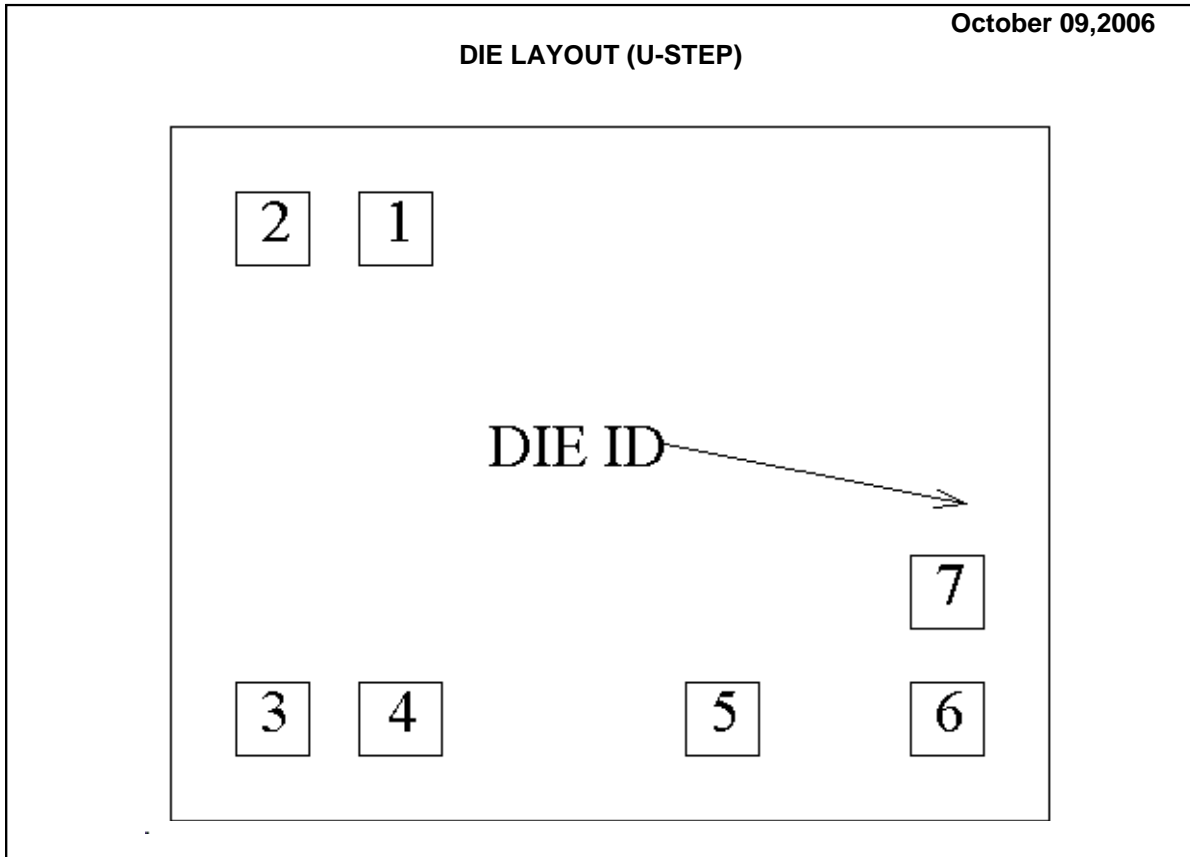


**LM741 MD8 MW8
OPERATIONAL AMPLIFIER**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	741U	Bond Pad Opening Size (min)	91µm x 91µm
Die Step	U	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1092µm x 864µm 43.0mils x 34.0mils	Back Side Connection	V -
Thickness	330µm Nominal		
Min Pitch	152µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (U -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OFFSET NULL	1	-267	305	91	x	91
INPUT -	2	-419	305	91	x	91
INPUT +	3	-419	-305	91	x	91
V -	4	-260	-305	104	x	91
OFFSET NULL	5	140	-305	91	x	91
OUTPUT	6	419	-305	91	x	91
V +	7	419	-147	91	x	91

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